

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® SuperSi series is based on Oriental Semiconductor's unique device design to achieve extremely fast switching characteristics. It is the perfect replacement for the Gallium Nitride (GaN) device in high frequency operations with better ruggedness and cost. It is targeted to meet the most aggressive efficiency standards of power supply systems by pushing both performance and power density to extreme limits.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Easy to design in



## Applications

- PD charger
- Large screen display
- Telecom power
- Server power

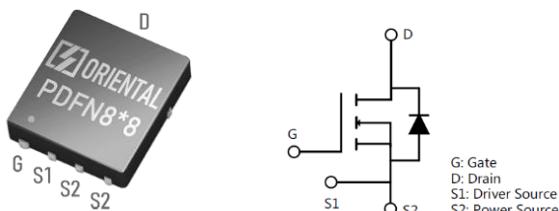
## Key Performance Parameters

| Parameter                      | Value | Unit |
|--------------------------------|-------|------|
| $V_{DS, min} @ T_{j(max)}$     | 650   | V    |
| $I_D, pulse$                   | 54    | A    |
| $R_{DS(ON), max} @ V_{GS}=10V$ | 190   | mΩ   |
| $Q_g$                          | 15.8  | nC   |

## Marking Information

| Product Name | Package  | Marking    |
|--------------|----------|------------|
| OSS60R190JF  | PDFN 8x8 | OSS60R190J |

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

| Parameter   | Symbol               | Value      | Unit |
|---|----------------------|------------|------|
| Drain-source voltage  | $V_{DS}$             | 600        | V    |
| Gate-source voltage   | $V_{GS}$             | $\pm 30$   | V    |
| Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$         | $I_D$                | 18         | A    |
| Continuous drain current <sup>1)</sup> , $T_C=100^\circ\text{C}$        |                      | 11.5       |      |
| Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$             | $I_{D,\text{pulse}}$ | 54         | A    |
| Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$ | $I_S$                | 18         | A    |
| Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$             | $I_{S,\text{pulse}}$ | 54         | A    |
| Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$                | $P_D$                | 110        | W    |
| Single pulsed avalanche energy <sup>5)</sup>                            | $E_{AS}$             | 360        | mJ   |
| MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$                  | dv/dt                | 50         | V/ns |
| Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$ , $I_{SD} \leq I_D$  | dv/dt                | 15         | V/ns |
| Operation and storage temperature                                       | $T_{stg}, T_j$       | -55 to 150 | °C   |

**Thermal Characteristics**

| Parameter  | Symbol          | Value | Unit |
|--|-----------------|-------|------|
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 1.14  | °C/W |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62    | °C/W |

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

| Parameter                        | Symbol              | Min. | Typ. | Max. | Unit          | Test condition   |
|----------------------------------|---------------------|------|------|------|---------------|--|
| Drain-source breakdown voltage   | $BV_{DSS}$          | 600  |      |      | V             | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$                           |
|                                  |                     | 650  |      |      |               | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$ , $T_j=150^\circ\text{C}$ |
| Gate threshold voltage           | $V_{GS(\text{th})}$ | 2.9  |      | 3.9  | V             | $V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$                               |
| Drain-source on-state resistance | $R_{DS(\text{ON})}$ |      | 0.16 | 0.19 | $\Omega$      | $V_{GS}=10\text{ V}$ , $I_D=5.6\text{ A}$                                    |
|                                  |                     |      | 0.27 |      |               | $V_{GS}=10\text{ V}$ , $I_D=5.6\text{ A}$ , $T_j=150^\circ\text{C}$          |
| Gate-source leakage current      | $I_{GSS}$           |      |      | 100  | nA            | $V_{GS}=30\text{ V}$   |
|                                  |                     |      |      | -100 |               | $V_{GS}=-30\text{ V}$  |
| Drain-source leakage current     | $I_{DSS}$           |      |      | 1    | $\mu\text{A}$ | $V_{DS}=600\text{ V}$ , $V_{GS}=0\text{ V}$                                  |
| Gate resistance                  | $R_G$               |      | 24.2 |      | $\Omega$      | f=1 MHz, Open drain  |

### Dynamic Characteristics

| Parameter                    | Symbol              | Min. | Typ.  | Max. | Unit | Test condition  |
|------------------------------|---------------------|------|-------|------|------|---|
| Input capacitance            | C <sub>iss</sub>    |      | 660.8 |      | pF   | V <sub>GS</sub> =0 V,<br>V <sub>DS</sub> =50 V,<br>f=1 MHz  |
| Output capacitance           | C <sub>oss</sub>    |      | 112.9 |      | pF   |   |
| Reverse transfer capacitance | C <sub>rss</sub>    |      | 3.5   |      | pF   |   |
| Turn-on delay time           | t <sub>d(on)</sub>  |      | 24.2  |      | ns   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =400 V,<br>R <sub>G</sub> =2 Ω,<br>I <sub>D</sub> =10 A |
| Rise time                    | t <sub>r</sub>      |      | 23.9  |      | ns   |   |
| Turn-off delay time          | t <sub>d(off)</sub> |      | 47.2  |      | ns   |   |
| Fall time                    | t <sub>f</sub>      |      | 6.3   |      | ns   |   |

### Gate Charge Characteristics

| Parameter            | Symbol               | Min. | Typ. | Max. | Unit | Test condition  |
|----------------------|----------------------|------|------|------|------|---|
| Total gate charge    | Q <sub>g</sub>       |      | 15.8 |      | nC   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =400 V,<br>I <sub>D</sub> =10 A |
| Gate-source charge   | Q <sub>gs</sub>      |      | 3.0  |      | nC   |   |
| Gate-drain charge    | Q <sub>gd</sub>      |      | 5.3  |      | nC   |   |
| Gate plateau voltage | V <sub>plateau</sub> |      | 6.3  |      | V    |   |

### Body Diode Characteristics

| Parameter                     | Symbol           | Min. | Typ.  | Max. | Unit | Test condition  |
|-------------------------------|------------------|------|-------|------|------|---|
| Diode forward voltage         | V <sub>SD</sub>  |      |       | 1.3  | V    | I <sub>S</sub> =18 A,<br>V <sub>GS</sub> =0 V                     |
| Reverse recovery time         | t <sub>rr</sub>  |      | 293.3 |      | ns   | V <sub>R</sub> =400 V,<br>I <sub>S</sub> =10 A,<br>di/dt=100 A/μs |
| Reverse recovery charge       | Q <sub>rr</sub>  |      | 3.5   |      | μC   |   |
| Peak reverse recovery current | I <sub>rrm</sub> |      | 23.9  |      | A    |   |

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=60 mH, starting T<sub>j</sub>=25 °C.

### Electrical Characteristics Diagrams

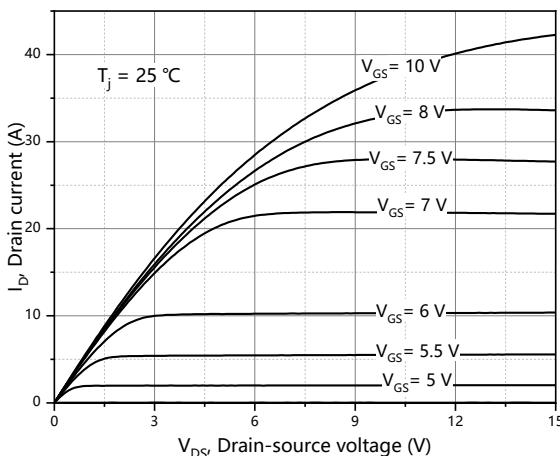


Figure 1. Typ. output characteristics

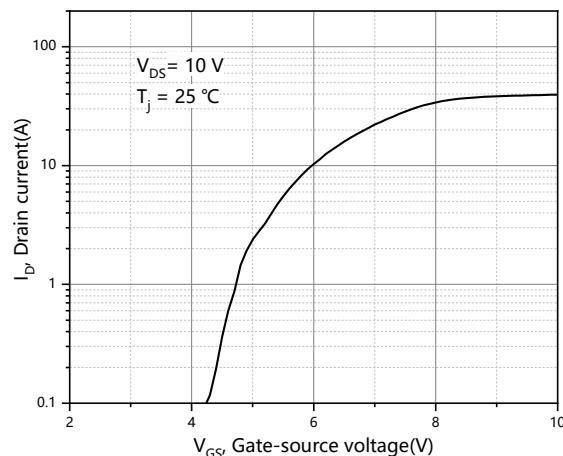


Figure 2. Typ. transfer characteristics

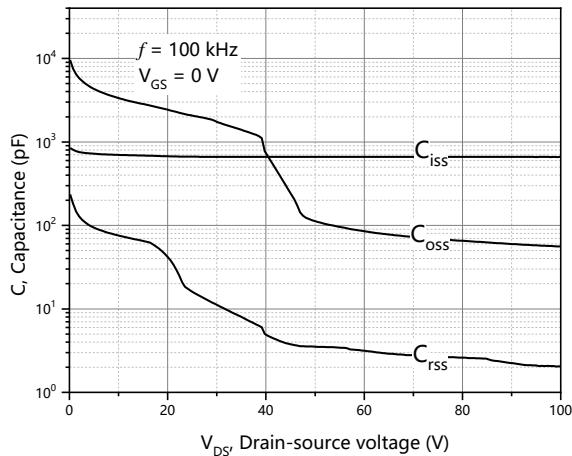


Figure 3. Typ. capacitances

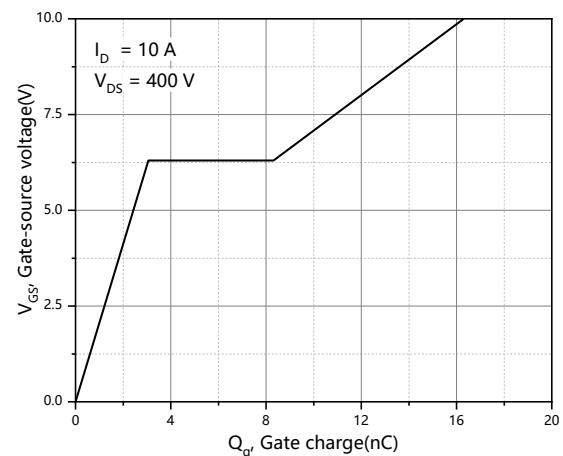


Figure 4. Typ. gate charge

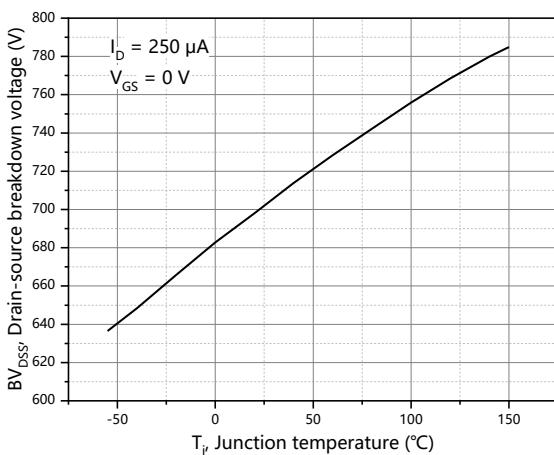


Figure 5. Drain-source breakdown voltage

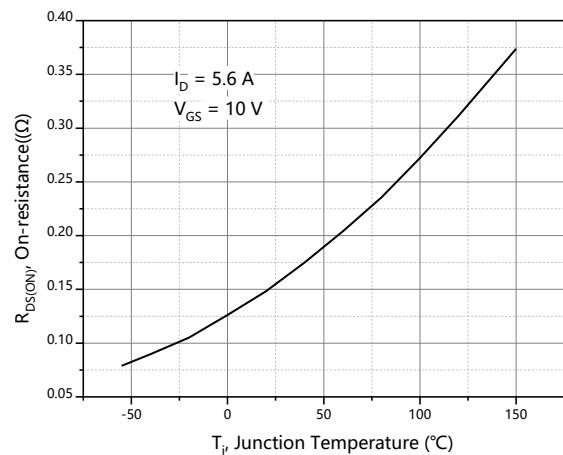
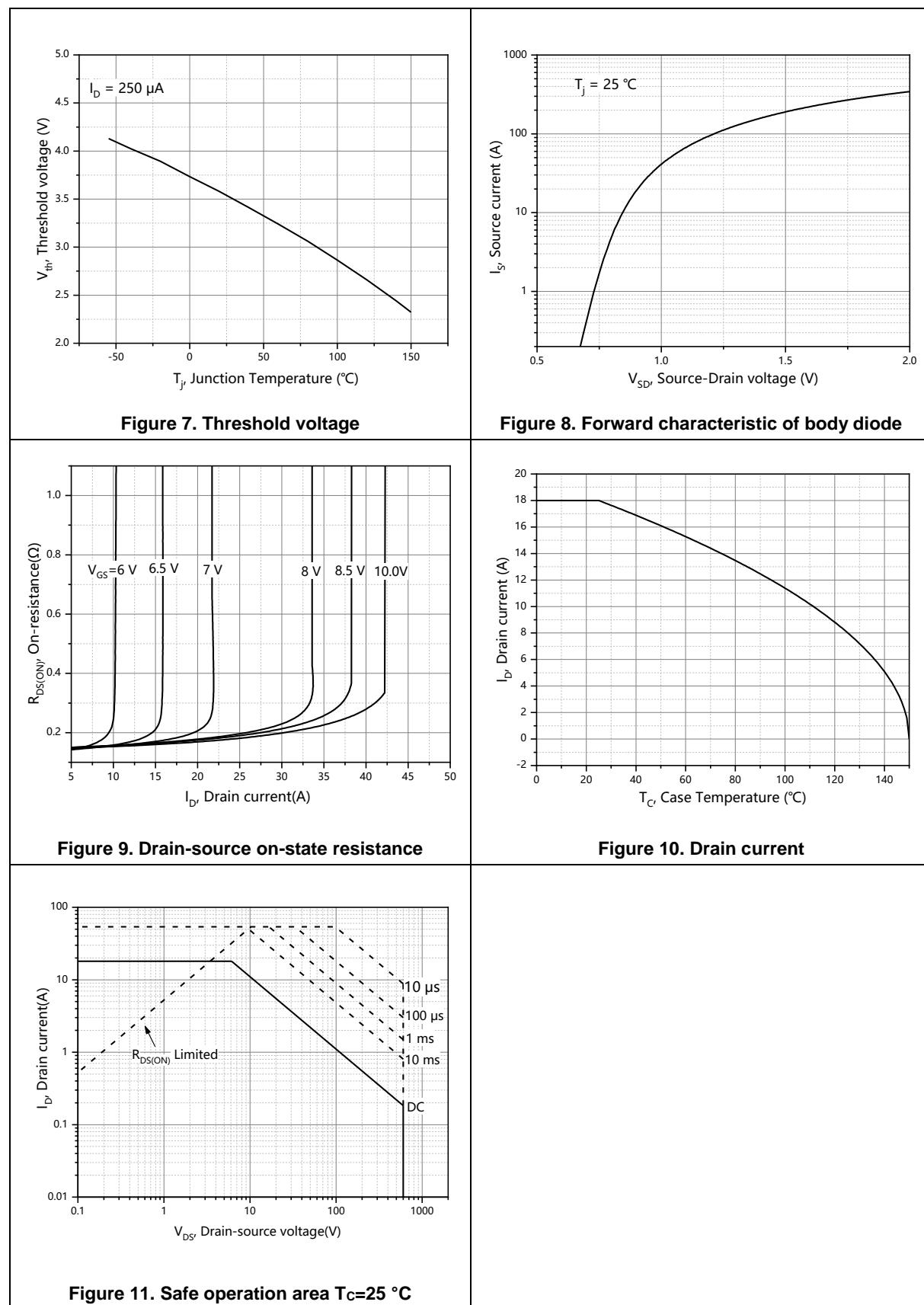


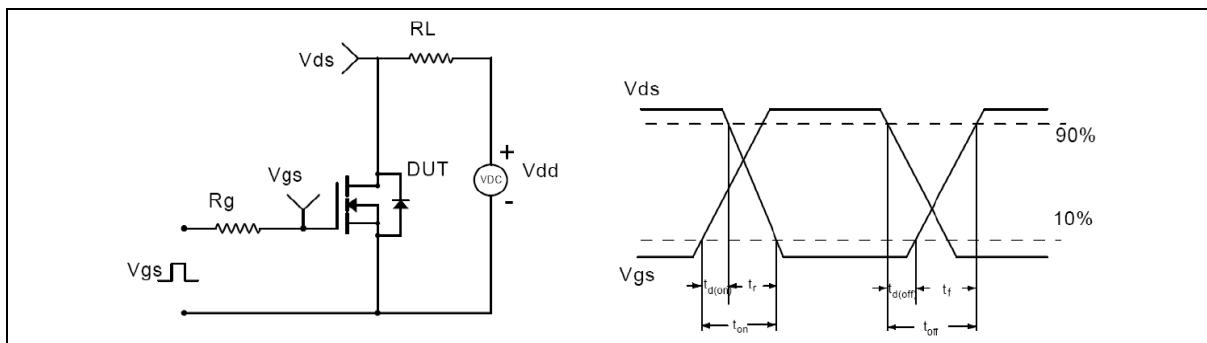
Figure 6. Drain-source on-state resistance



### Test circuits and waveforms



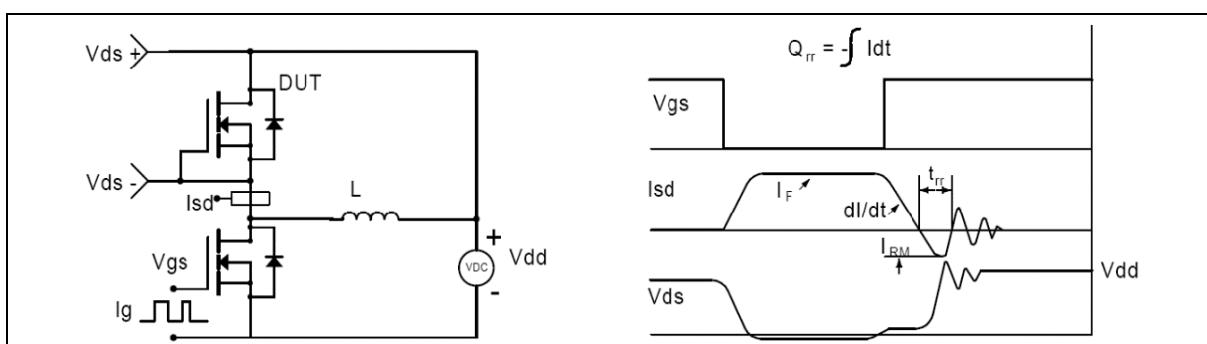
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

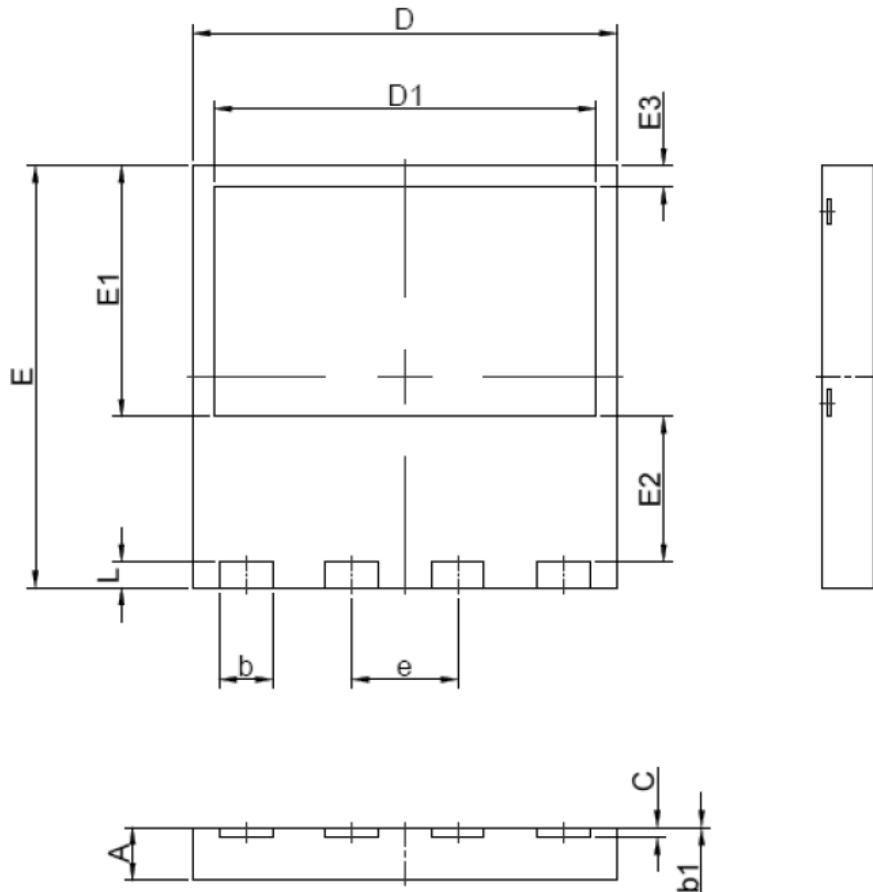


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

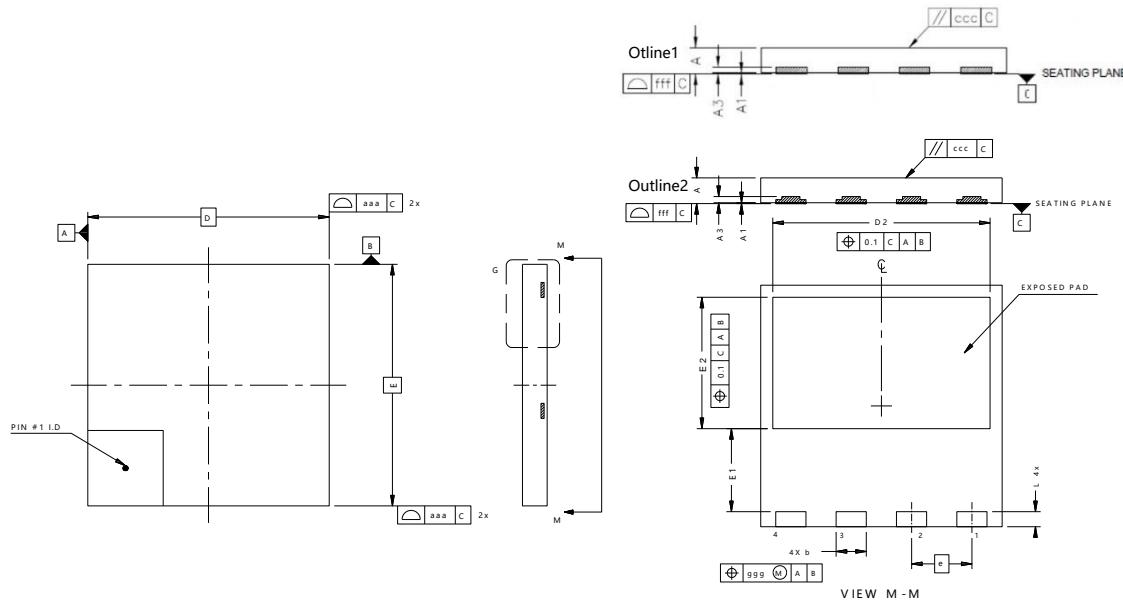
### Package Information



| Symbol | mm     |      |      |
|--------|--------|------|------|
|        | Min    | Nom  | Max  |
| A      | 0.90   | 1.00 | 1.10 |
| b      | 0.90   | 1.00 | 1.10 |
| b1     | 0.00   | 0.02 | 0.05 |
| C      | 0.2REF |      |      |
| D      | 7.90   | 8.00 | 8.10 |
| D1     | 7.10   | 7.20 | 7.30 |
| E      | 7.90   | 8.00 | 8.10 |
| E1     | 4.65   | 4.75 | 4.85 |
| E2     | 2.65   | 2.75 | 2.85 |
| E3     | 0.30   | 0.40 | 0.50 |
| e      | 2.0BSC |      |      |
| L      | 0.40   | 0.50 | 0.60 |

Version 1: PDFN 8x8-L package outline dimension

## Package Information



| Symbol | mm      |      |
|--------|---------|------|
|        | Min     | Max  |
| A      | 0.75    | 0.95 |
| A1     | 0.00    | 0.05 |
| A3     | 0.10    | 0.30 |
| b      | 0.90    | 1.10 |
| D      | 7.90    | 8.10 |
| E      | 7.90    | 8.10 |
| D2     | 7.10    | 7.30 |
| E1     | 2.65    | 2.85 |
| E2     | 4.25    | 4.45 |
| e      | 2.0 BSC |      |
| L      | 0.40    | 0.60 |
| aaa    | 0.1     |      |
| ggg    | 0.05    |      |
| ccc    | 0.05    |      |
| fff    | 0.05    |      |

Version 2: POFN 8x8-S package outline dimension

## Ordering Information

| Package Type | Units/Reel | Reels/Inner Box | Units/Inner Box | Inner Boxes/Carton Box | Units/Carton Box |
|--------------|------------|-----------------|-----------------|------------------------|------------------|
| PDFN 8x8-L   | 2500       | 1               | 2500            | 10                     | 25000            |
| PDFN 8x8-S   | 3000       | 1               | 3000            | 10                     | 30000            |

## Product Information

| Product     | Package  | Pb Free | RoHS | Halogen Free |
|-------------|----------|---------|------|--------------|
| OSS60R190JF | PDFN 8x8 | yes     | yes  | yes          |

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